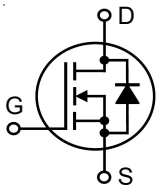
IXYS

X4-Class Power MOSFET™

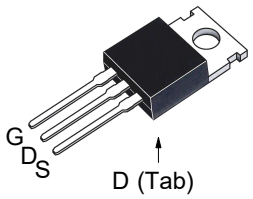
IXTP86N20X4

V_{DSS} = 200V
I_{D25} = 86A
$R_{DS(on)}$ ≤ 13mΩ

N-Channel Enhancement Mode
Avalanche Rated



TO-220 (IXTP)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	200	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	200	V
V_{GS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	86	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	160	A
I_A	T_C = 25°C	43	A
E_{AS}	T_C = 25°C	500	mJ
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	50	V/ns
P_D	T_C = 25°C	300	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	Maximum Lead Temperature for Soldering 1.6 mm (0.062 in.) from Case for 10s	300	°C
M_d	Mounting Torque	1.13 / 10	Nm/lb.in
Weight		3	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 250μA	2.5		4.5	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			5	μA
	T_J = 150°C			300	μA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1		11	13	mΩ

Features

- International Standard Package
- Low $R_{DS(ON)}$ and Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 0.5 • I_{D25}, Note 1	50	82		S
R_{Gi}	Gate Input Resistance		4.75		Ω
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		2250		pF
C_{oss}			660		pF
C_{rss}			185		pF
$t_{d(on)}$	**Resistive Switching Times**		27		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		38		ns
$t_{d(off)}$	R_G = 10Ω (External)		76		ns
t_f			35		ns
$Q_{g(on)}$	V_{GS}= 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		70		nC
Q_{gs}			20		nC
Q_{gd}			38		nC
R_{thJC}				0.50	°C/W
R_{thJC}			0.50		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			86	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			344	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.4	V
t_{rr}	I_F = 43A, -di/dt = 100A/μs,		110		ns
I_{RM}	V_R = 100V		0.5		A
Q_{RM}			9.4		μC

Note 1: Pulse test, t ≤ 300μs, duty cycle, d ≤ 2 %

Fig. 1. Output Characteristics @ T_J = 25ºC

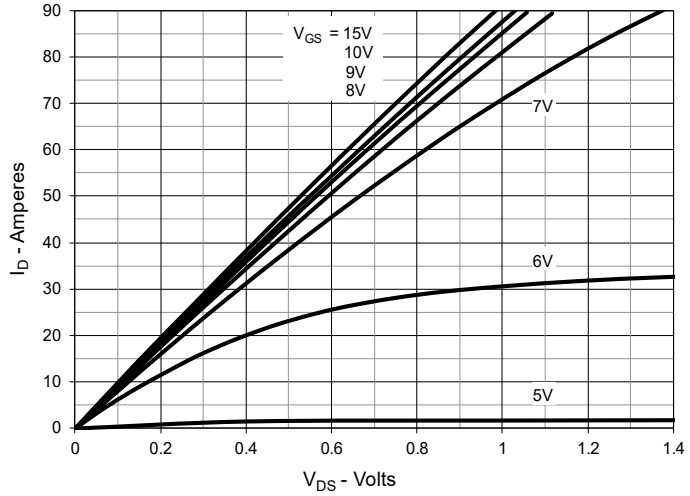


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

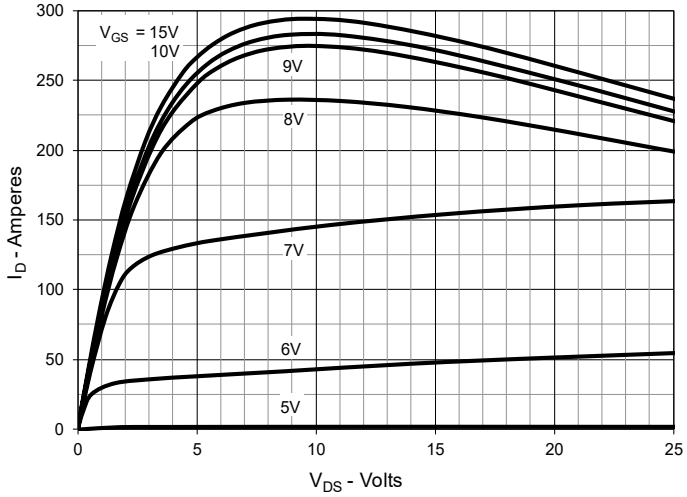


Fig. 3. Output Characteristics @ T_J = 150ºC

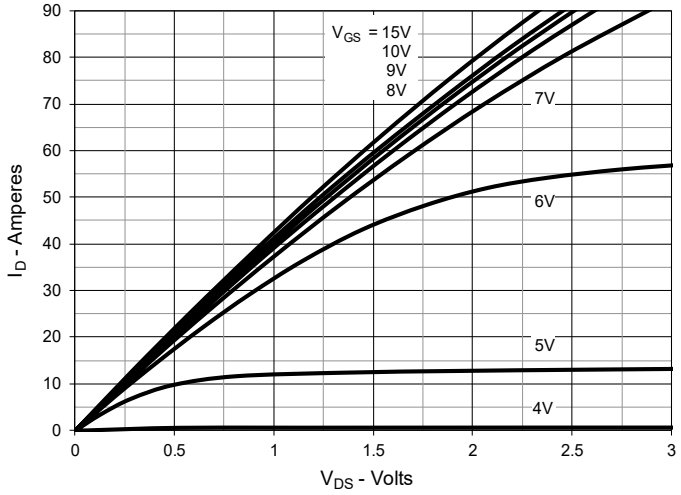


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 43A Value vs. Junction Temperature

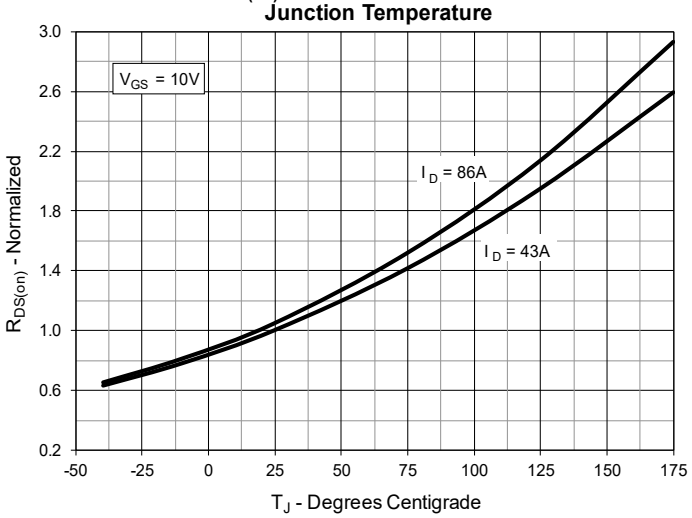


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 43A Value vs. Drain Current

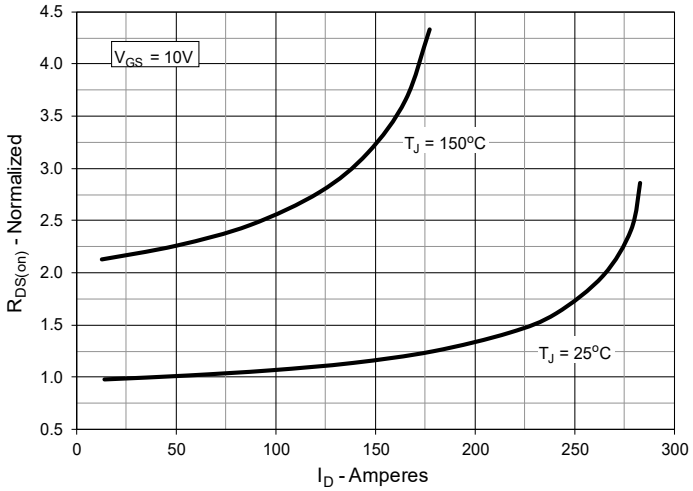


Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

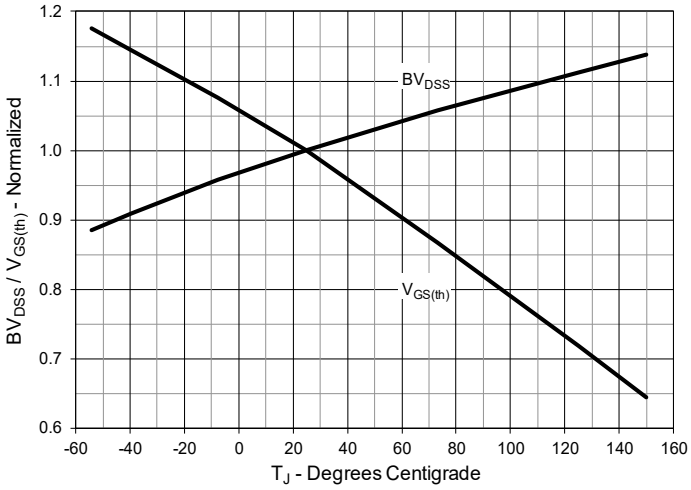


Fig. 7. Maximum Drain Current vs. Case Temperature

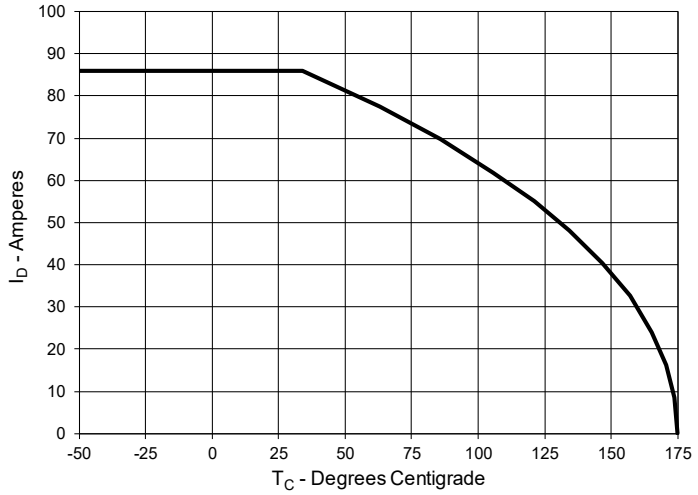


Fig. 8. Input Admittance

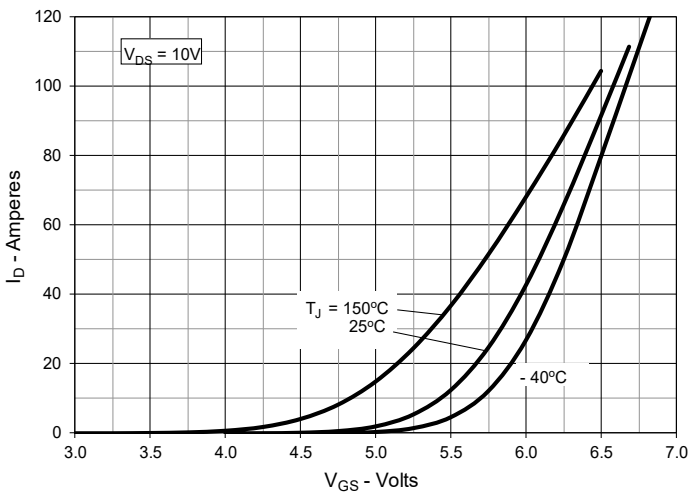


Fig. 9. Transconductance

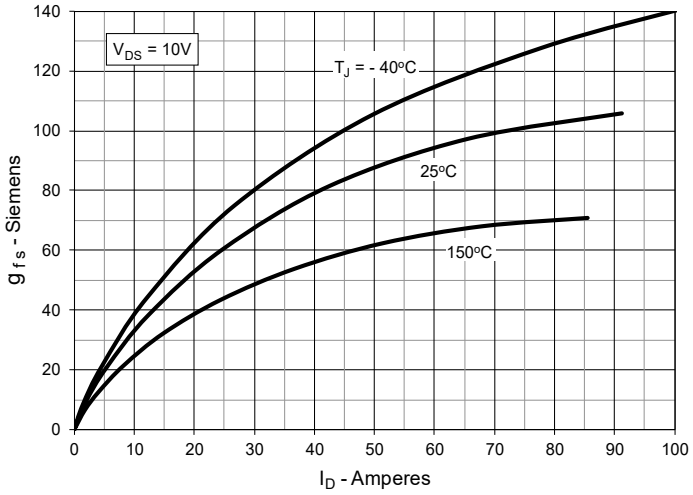


Fig. 10. Forward Voltage Drop of Intrinsic Diode

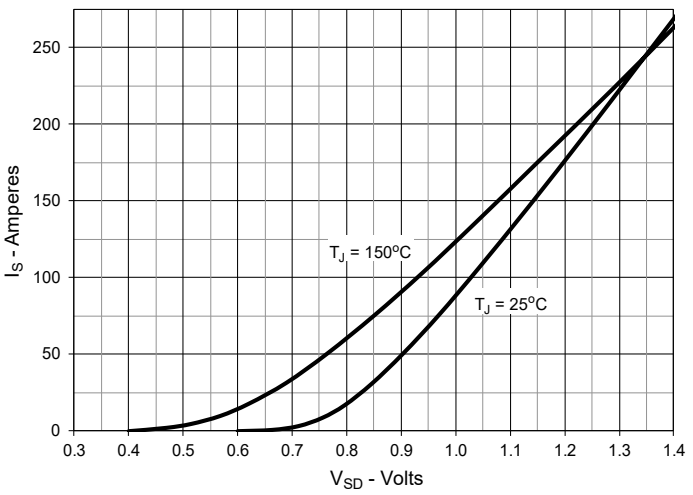


Fig. 11. Gate Charge

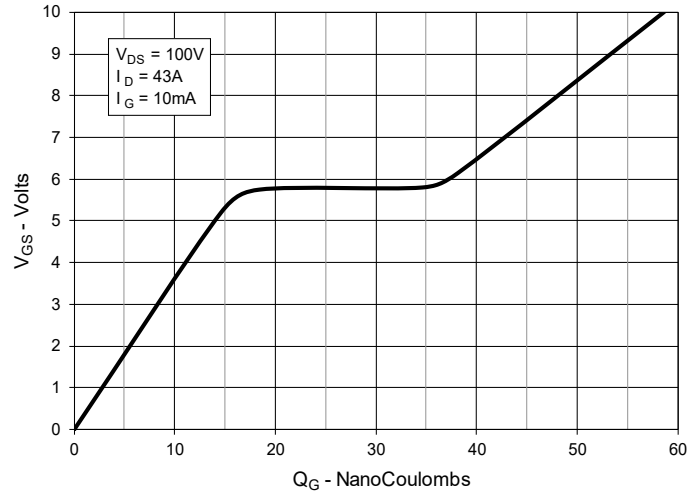


Fig. 12. Capacitance

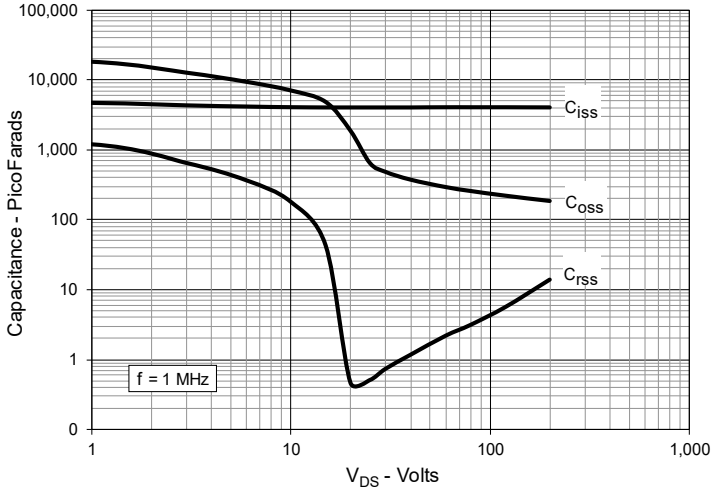


Fig. 13. Output Capacitance Stored Energy

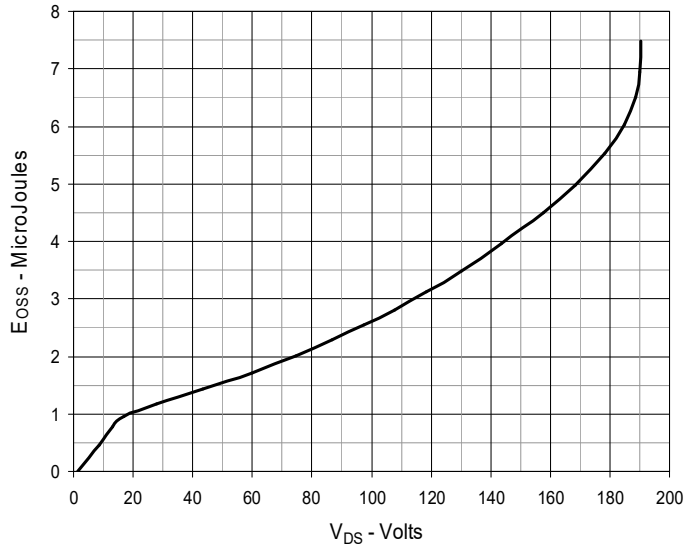


Fig. 14. Forward-Bias Safe Operating Area

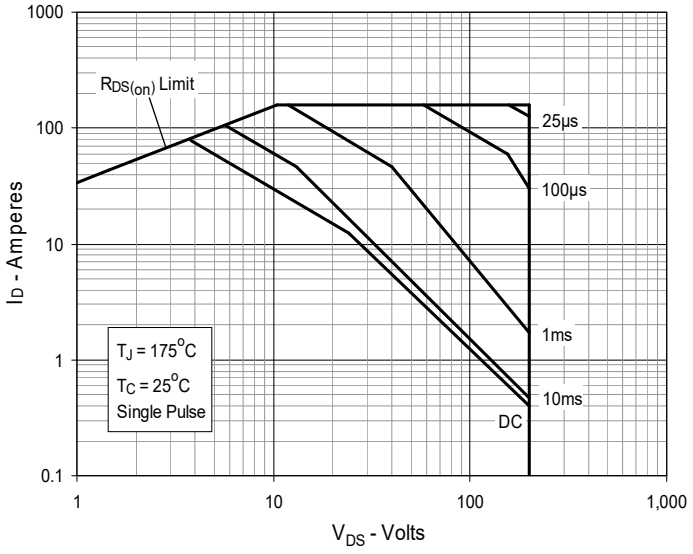
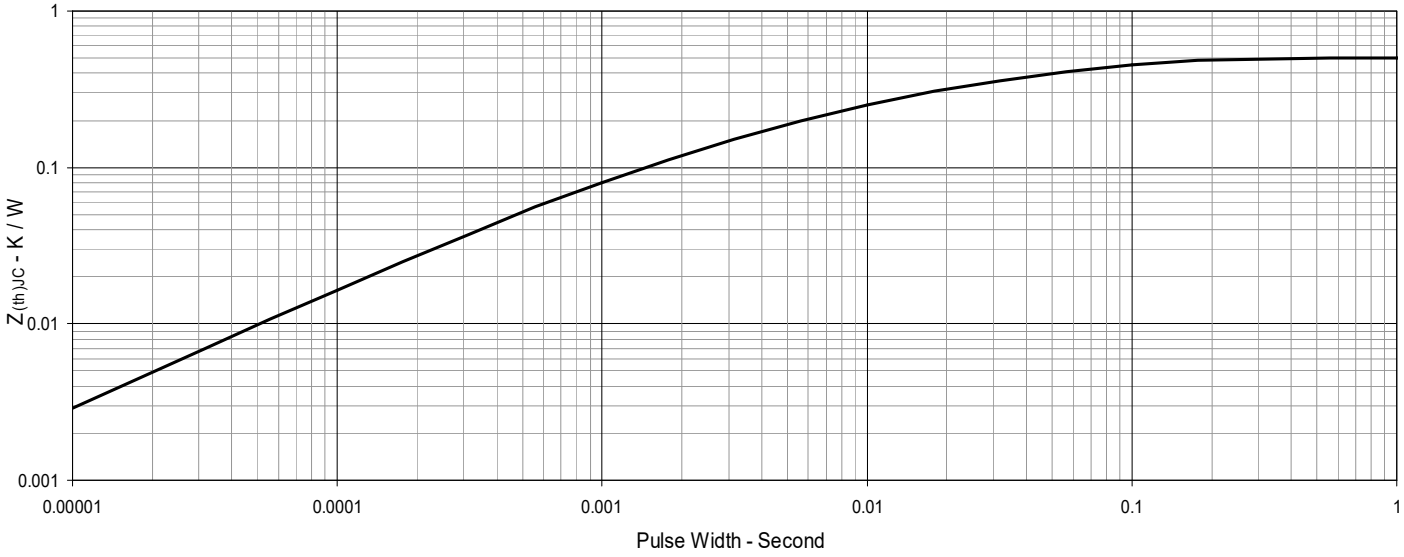
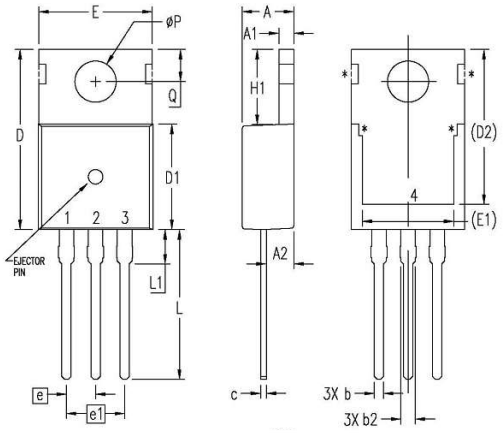
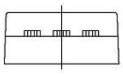


Fig. 15. Maximum Transient Thermal Impedance



TO-220 Outline





1 - Gate
2,4 - Drain
3 - Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
b	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
c	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
E	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
e	.100 BSC		2.54 BSC	
e1	.200 BSC		5.08 BSC	
H1	.244	.268	6.20	6.80
L	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
øP	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20

NOTE:
1. These dimensions do not inclue mold protusion.
2. Metal finish – Matte pure tin plating except trim area.
3. Pin call out: 1 – GATE 3 – SOURCE (EMITTER for IGBT)
   2 – DRAIN (COLLECTOR for IGBT) 4 – DRAIN (Connected with #2 internally)
4. Ejector pin location & diameter will vary depending on packaging suppliers.
5. * marked area will vary depending on packaging suppliers.

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